Process Flow, Electrical

Applicable for Z770i

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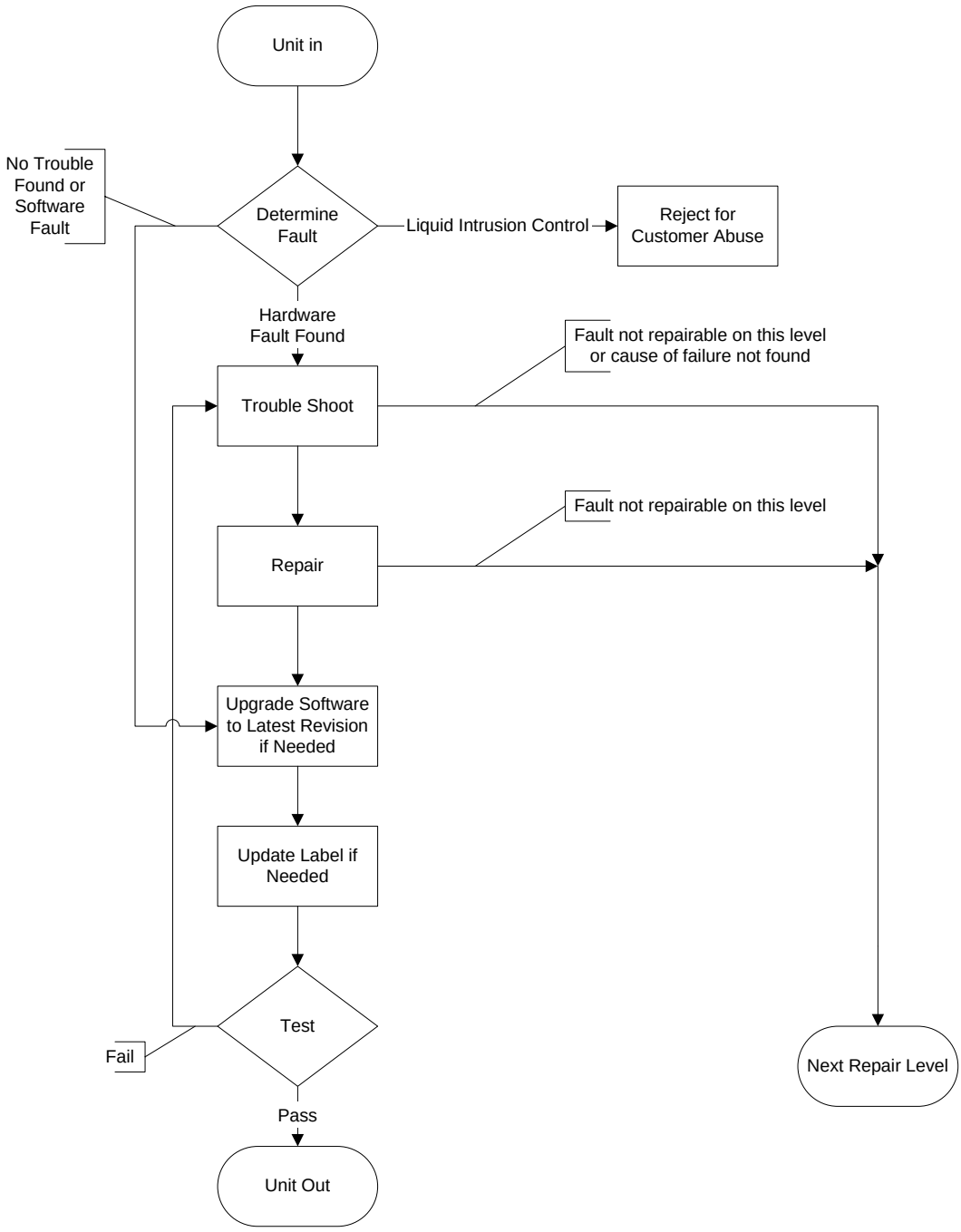
1 Process Flow



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1.1 Process Flow, Description

Box	Reference
Unit in	Process the phone according to local requirements.
Determine Fault	***Test Instruction, Mechanical and Electrical*** Determine if the phone is faulty or not, and try to confirm the customer's complaint. Only perform those tests necessary to confirm the failure. If a hardware fault is found, or a hardware and software fault is found, then continue with **Trouble Shoot.** If only a software fault is found, then continue with **Upgrade Software to Latest Revision, Test,** and **Unit Out.** **Report as *SW upgrade.*** If no hardware or software fault is found, then continue with **Upgrade Software to Latest Revision, Test,** and **Unit Out.** **Report as *No Trouble Found, NTF.*** If liquid intrusion or other abuse is found, then continue with **Reject for Customer Abuse.**
Reject for Customer Abuse	***Test Instruction, Mechanical*** If liquid intrusion or abuse is found, then reject the product according to local requirements.
Trouble Shoot	***Trouble Shooting Guide, Mechanical and Electrical*** Determine the cause of the failure. Trouble-shoot the phone according to the guide for the most common faults.
Repair	***Working Instruction, Mechanical and Electrical*** Repair the faulty phone according to the instruction. Replace parts as required. ***(Product Change Survey, Mechanical)*** Flashing the latest software into the phone at this point may "repair" some problems. If a repair that requires calibration has been done, then calibrate the unit in SERP. ***(Test Instruction, Electrical)*** ***Calibration can only be done by authorized repair locations.***
Upgrade Software to Latest Revision if Needed	***Product Change Survey, Mechanical*** Upgrade the software to the latest revision if needed.
Update Label if Needed	***Working Instruction Mechanical*** Print and apply a new label if needed.
Test	***Test Instruction, Mechanical and Electrical*** Perform all tests as described in the instruction.
Unit Out	Process and package the phone according to local requirements.
Next Repair Level	If the cause of the failure cannot be found or is not reparable at this level, then the product can be Scrapped, Swapped, or returned to the customer at the customer's request. Scrap: According to local directives Swap: Swap the phone according to the instruction in ***Working Instructions, Swap and Customize*** and according to local directives***.***

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2 Revision History

Rev.	Date	Changes / Comments
1	2008-03-13	First Released

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